

MBRB20200CTG, SBRB20200CTT4G

Switch-mode Power Rectifier

Dual Schottky Rectifier

This device uses the Schottky Barrier technology with a platinum barrier metal. This state-of-the-art device is designed for use in high frequency switching power supplies and converters with up to 48 V outputs. They block up to 200 V and offer improved Schottky performance at frequencies from 250 kHz to 5.0 MHz.

Features

- 200 V Blocking Voltage
- Low Forward Voltage Drop
- Guardring for Stress Protection and High dv/dt Capability (10,000 V/ μ s)
- Dual Diode Construction – Terminals 1 and 3 Must be Connected for Parallel Operation at Full Rating
- AEC-Q101 Qualified and PPAP Capable
- SBRB Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- All Packages are Pb-Free*

Mechanical Characteristics:

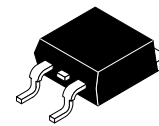
- Case: Epoxy, Molded, Epoxy Meets UL 94 V-0
- Weight: 1.7 Grams (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Device Meets MSL1 Requirements
- ESD Rating:
 - ◆ Human Body Model = 3B
 - ◆ Machine Model = C



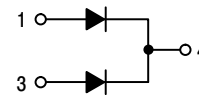
ON Semiconductor®

<http://onsemi.com>

**SCHOTTKY BARRIER
RECTIFIER
20 AMPERES, 200 V**



**D²PAK
CASE 418B**



MARKING DIAGRAM



A = Assembly Location
Y = Year
WW = Work Week
B20200 = Device Code
G = Pb-Free Package
AKA = Diode Polarity

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MBRB20200CTG, SBRB20200CTT4G

MAXIMUM RATINGS (Per Leg)

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	200	V
Average Rectified Forward Current (At Rated V_R , $T_C = 134^\circ\text{C}$) Per Leg Per Device	$I_{F(AV)}$	10 20	A
Peak Repetitive Forward Current (At Rated V_R , Square Wave, 20 kHz, $T_C = +137^\circ\text{C}$) Per Leg	I_{FRM}	20	A
Nonrepetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I_{FSM}	150	A
Peak Repetitive Reverse Surge Current (2.0 μs , 1.0 kHz)	I_{RRM}	1.0	A
Storage Temperature Range	T_{stg}	-65 to +175	$^\circ\text{C}$
Operating Junction Temperature	T_J	-65 to +150	$^\circ\text{C}$
Voltage Rate of Change (Rated V_R)	dv/dt	10,000	V/ μs

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS (Per Leg)

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	2.0	$^\circ\text{C/W}$

ELECTRICAL CHARACTERISTICS (Per Leg)

Characteristic	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage (Note 1) ($I_F = 10\text{ A}$, $T_C = 25^\circ\text{C}$) ($I_F = 10\text{ A}$, $T_C = 125^\circ\text{C}$) ($I_F = 20\text{ A}$, $T_C = 25^\circ\text{C}$) ($I_F = 20\text{ A}$, $T_C = 125^\circ\text{C}$)	V_F	0.9 0.8 1.0 0.9	V
Maximum Instantaneous Reverse Current (Note 1) (Rated dc Voltage, $T_C = 25^\circ\text{C}$) (Rated dc Voltage, $T_C = 125^\circ\text{C}$)	I_R	1.0 50	mA

DYNAMIC CHARACTERISTICS (Per Leg)

Characteristic	Symbol	Value	Unit
Capacitance ($V_R = -5.0\text{ V}$, $T_C = 25^\circ\text{C}$, Frequency = 1.0 MHz)	C_T	500	pF

1. Pulse Test: Pulse Width = 300 μs , Duty Cycle $\leq 2.0\%$.

ORDERING INFORMATION

Device	Package	Shipping [†]
MBRB20200CTG	D ² PAK (Pb-Free)	50 Units / Rail
MBRB20200CTT4G	D ² PAK (Pb-Free)	800 Units / Tape & Reel
SBRB20200CTT4G	D ² PAK (Pb-Free)	800 Units / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MBRB20200CTG, SBRB20200CTT4G

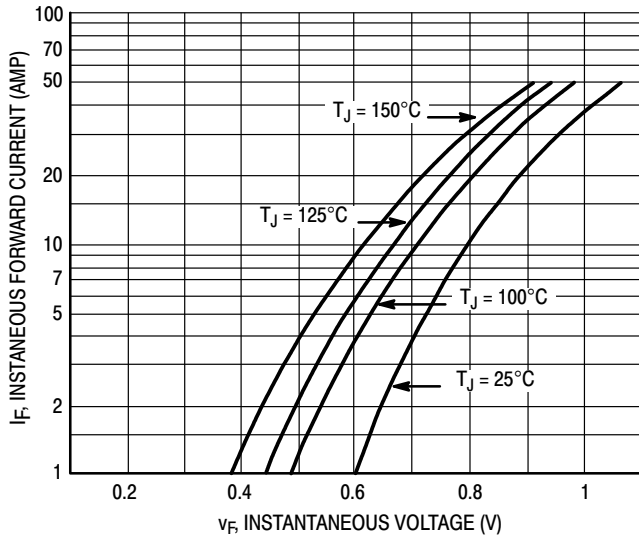


Figure 1. Typical Forward Voltage (Per Leg)

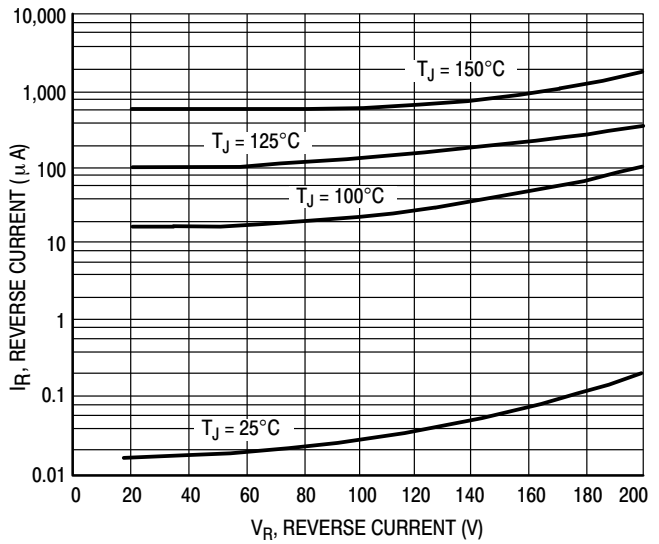


Figure 2. Typical Reverse Current (Per Leg)

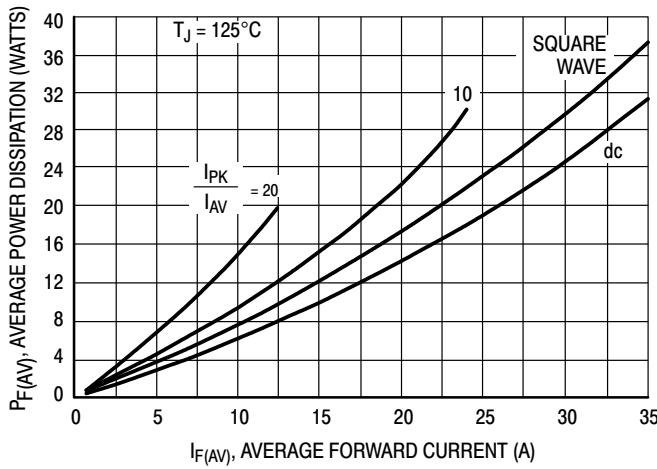


Figure 3. Forward Power Dissipation

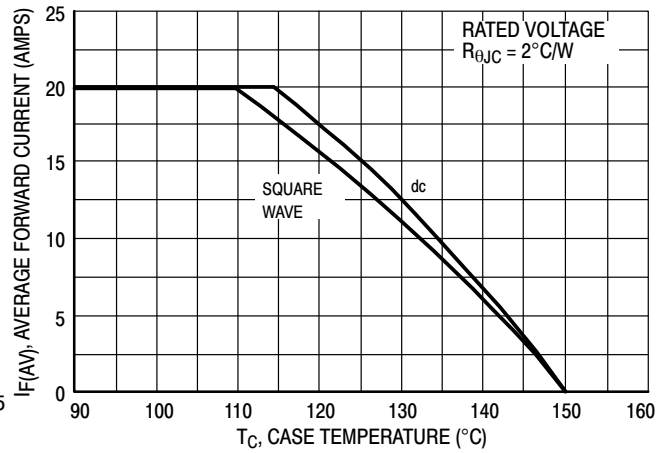


Figure 4. Current Derating, Case

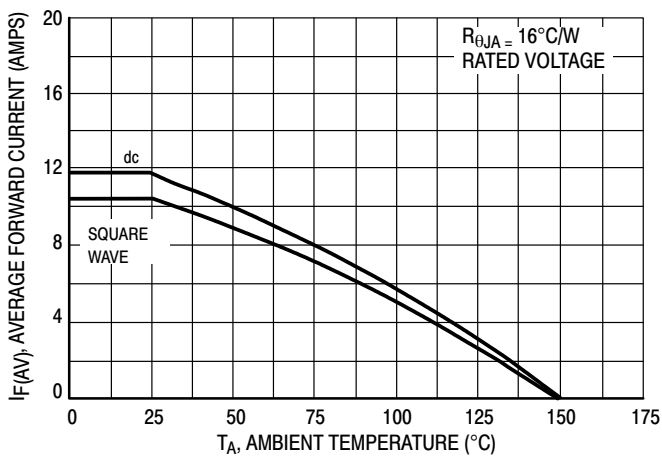


Figure 5. Current Derating, Ambient

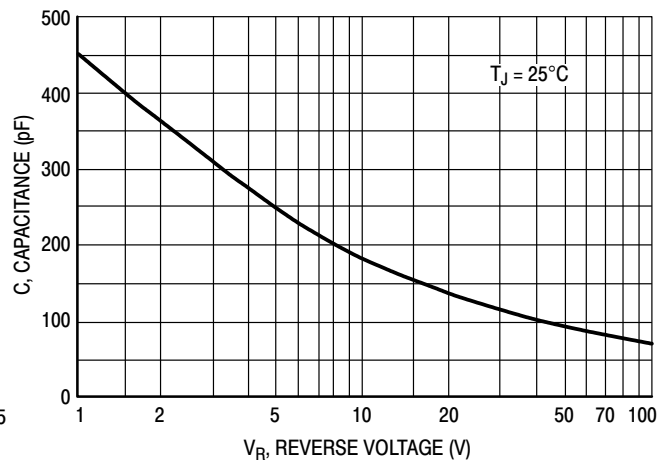


Figure 6. Typical Capacitance (Per Leg)

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®



D²PAK 3
CASE 418B-04
ISSUE L

DATE 17 FEB 2015

SCALE 1:1

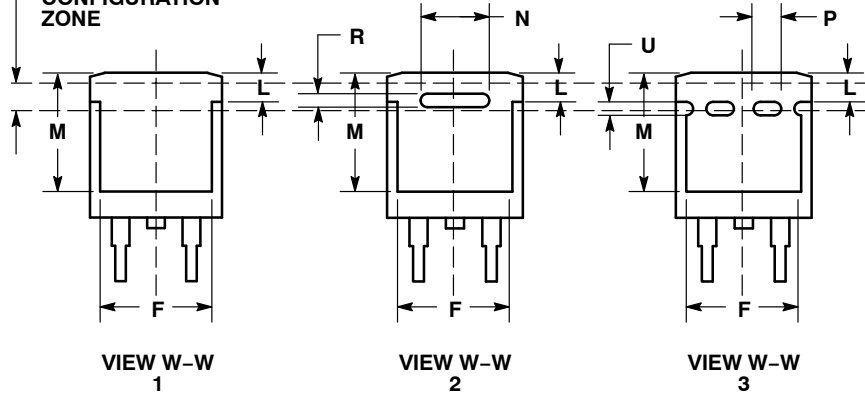


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. 418B-01 THRU 418B-03 OBSOLETE, NEW STANDARD 418B-04.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.340	0.380	8.64	9.65
B	0.380	0.405	9.65	10.29
C	0.160	0.190	4.06	4.83
D	0.020	0.035	0.51	0.89
E	0.045	0.055	1.14	1.40
F	0.310	0.350	7.87	8.89
G	0.100	BSC	2.54	BSC
H	0.080	0.110	2.03	2.79
J	0.018	0.025	0.46	0.64
K	0.090	0.110	2.29	2.79
L	0.052	0.072	1.32	1.83
M	0.280	0.320	7.11	8.13
N	0.197	REF	5.00	REF
P	0.079	REF	2.00	REF
R	0.039	REF	0.99	REF
S	0.575	0.625	14.60	15.88
V	0.045	0.055	1.14	1.40

VARIABLE CONFIGURATION ZONE



- | | | | | | |
|------------------------------------------------------------------------------|---------------------------------------------------------------------|-------------------------------------------------------------------------|------------------------------------------------------------------------------|-------------------------------------------------------------------------|------------------------------------------------------------------------------|
| STYLE 1:
PIN 1. BASE
2. COLLECTOR
3. EMITTER
4. COLLECTOR | STYLE 2:
PIN 1. GATE
2. DRAIN
3. SOURCE
4. DRAIN | STYLE 3:
PIN 1. ANODE
2. CATHODE
3. ANODE
4. CATHODE | STYLE 4:
PIN 1. GATE
2. COLLECTOR
3. EMITTER
4. COLLECTOR | STYLE 5:
PIN 1. CATHODE
2. ANODE
3. CATHODE
4. ANODE | STYLE 6:
PIN 1. NO CONNECT
2. CATHODE
3. ANODE
4. CATHODE |
|------------------------------------------------------------------------------|---------------------------------------------------------------------|-------------------------------------------------------------------------|------------------------------------------------------------------------------|-------------------------------------------------------------------------|------------------------------------------------------------------------------|

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D²PAK 3
CASE 418B-04
ISSUE L

DATE 17 FEB 2015

**GENERIC
MARKING DIAGRAM***



- xx = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- Y = Year
- WW = Work Week
- G = Pb-Free Package
- AKA = Polarity Indicator

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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